











- ► DC Input Photo Coupler
- ► SMD6 Low Profile
- ➤ Random-Phase TRIAC

TD307X(SL)(T1)-GV





# TD307X(SL) Series

#### **DESCRIPTION:**





The TD307X(SL) series combine an AlGaAs infrared emitting diode as the emitter which is optically coupled to a monolithic silicon random-phase photo TRIAC in a plastic DIP6 package with SMD6 Low Profile lead forming option.

With the robust coplanar double mold structure, TD307X(SL) series provide the most stable isolation feature.

#### **APPLICATIONS:**

- Solenoid/valve controls
- Lighting controls
- Motor controls
- Temperature controls
- Static AC power switches
- Solid state relays
- Interfacing microprocessors to 115 to 240VAC peripherals

## **FEATURES:**

- High isolation 5000Vrms
- DC input with random-phase photo TRIAC output
- Operating temperature range -40°C to +100°C
- REACH & RoHS compliance
- MSL class 1
- Regulatory Approvals:
  - o UL UL1577
  - o VDE EN60747-5-5 (VDE0884-5)
  - o CQC GB4943.1, GB8898
  - o cUL CSA Component Acceptance Service Notice 5A

Packing: 1000pcs/reel







Release Date: 26 June 2025 Version: A00

(B)



## **NAMING & ORDERING INFORMATION:**

## Naming Information:

TD307 X (SL) (T1) - G V		
TD307X	Part Number	
×	Selection: LED Trigger Current (X=1~3)	
SL	Lead Form Option: SMD6 Low Profile	
T1	Selection: Tape and Reel Option (T1(default)/T2)	
G	Green Option	
V	VDE Option	

## Ordering Information:

# **TD307**<u>X</u>(SL)(T1)-GV

 $\underline{X}$  = Selection: LED Trigger Current (X=1~3)

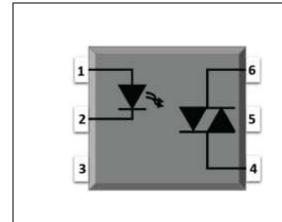
Part Number	Symbol	Values			Unit	Test Condition
Part Nulliber	Зуппоп	Min.	Тур.	Max.	Offic	rest Condition
TD3071(SL)(T1)-GV				15		L =100m A
TD3072(SL)(T1)-GV	I <sub>FT</sub>			10	mA	I <sub>™</sub> =100mA Terminal Voltage=3V
TD3073(SL)(T1)-GV				5		voitage=5v

Version No.	Original Release Date		
Rev: A00	05/09/2024		



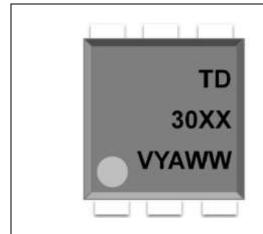
## **SCHEMATIC DIAGRAM & MARKING:**

## Schematic Diagram:



PIN Definition			
1	Anode		
2	Cathode		
3	NC		
4	Terminal		
5	Substrate		
6	Terminal		

## Marking Information:



	Marking Definition
TD	Manufacturer Code
307X	Part Number & Rank
V	VDE Applicable
Υ	Fiscal Year
А	Manufacturing Code
ww	Work Week

## **Labelling Information:**



This product is manufactured, tested, and packed by



for more details, please visit www.tdled.com



## **ABSOLUTE CHARACTERISTICS:**

## Absolute Maximum Ratings:

Parameter	Symbol	Ratings	Unit
	INPUT		
Forward Current	lF	60	mA
Reverse Voltage	VR	6	V
Junction Temperature	Tj	125	°C
Input Power Dissipation	P <sub>I</sub>	100	mW
	OUTPUT		
Off-State Output Terminal Voltage	V <sub>DRM</sub>	800	V
Peak Repetitive Surge Current PW=100µs, 120pps	Ітѕм	1	А
On-State RMS Current	I <sub>T</sub> (RMS)	100	mA
Junction Temperature	Tj	125	°C
Output Power Dissipation	Po	300	mW
	COMMON		
Total Power Dissipation	P <sub>tot</sub>	400	mW
Isolation Voltage	V <sub>iso</sub>	5000 *1	Vrms
Operating Temperature	Topr	-40~+100	°C
Storage Temperature	T <sub>stg</sub>	-55~+125	°C
Soldering Temperature	T <sub>sol</sub>	260 *²	°C

<sup>\*1.</sup> AC for 1 minute, R.H.= $40^{\circ}60\%$ .

<sup>\*2.</sup> For 10 seconds max.



## **ELECTRICAL CHARACTERISTICS:**

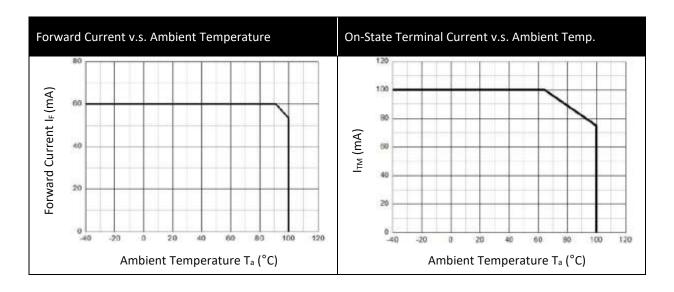
Electrical Optical Characteristics at T<sub>a</sub>=25°C:

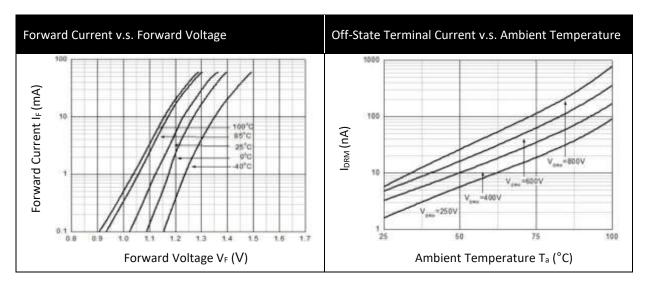
Paramete	r	Symbol	Min.	Values Typ.	Max.	Unit	Test Condition
		'	INPU				
Forward Voltage		V <sub>F</sub>		1.24	1.4	V	I <sub>F</sub> =10mA
Reverse Current		I <sub>R</sub>			10	μΑ	V <sub>R</sub> =6V
Input Capacitance		Cin		8.5	250	pF	V=0, f=1kHz
			OUTPL	JT			
Peak Off-State Current Either Direction	nt	I <sub>DRM</sub>			100 *1	nA	V <sub>DRM</sub> =Rated V <sub>DRM</sub> I <sub>F</sub> =0
Peak On-State Voltage Either Direction	e	V <sub>TM</sub>		1.58	2.5	V	I <sub>TM</sub> =100mA
Critical Rate of Rise of Voltage	f Off-State	dV/dt	1000			V/µs	V <sub>PEAK</sub> =400V I <sub>F</sub> =0
		TRAN	NSFER CHAR	ACTERISTICS			
	TD3071				15		100 1
LED Trigger Current	TD3072	I <sub>FT</sub>			10	mA	I <sub>TM</sub> =100mA Terminal
TD307	TD3073				5		Voltage=3V
Holding Current		lн		257		μΑ	
Isolation Resistance		R <sub>ISO</sub>	10^12	10^14		Ω	DC=500V, 40~60% R.H.
Floating Capacitance		Сю		0.8		pF	V=0, f=1MHz

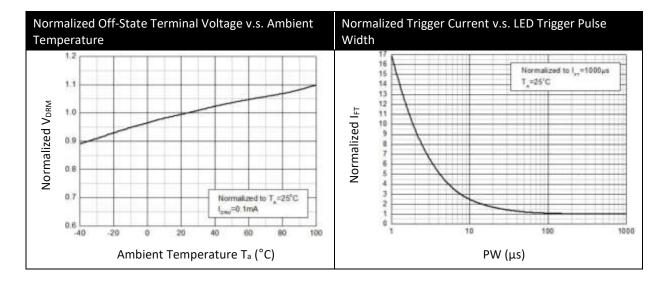
 $<sup>^{*}</sup>$ 1. Test voltage must be applied within dV/dt rating.



#### **CHARACTERISTIC CURVES:**

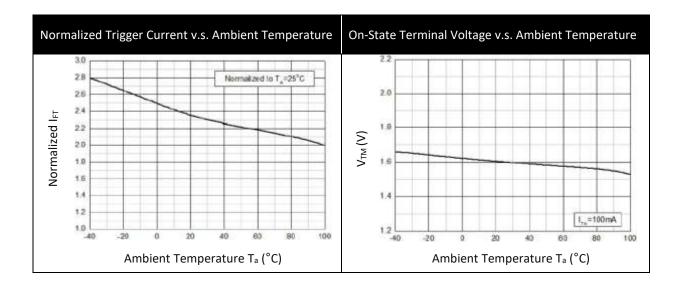


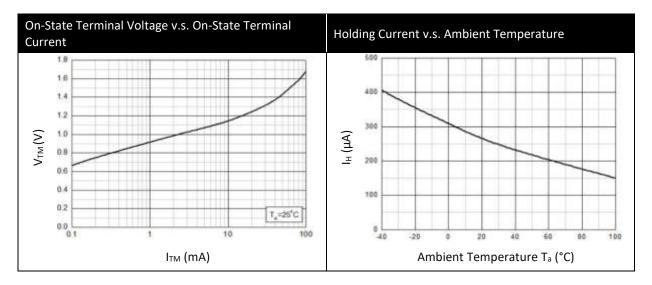


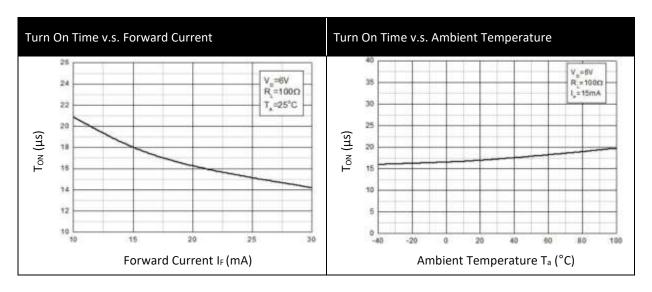




#### **CHARACTERISTIC CURVES:**



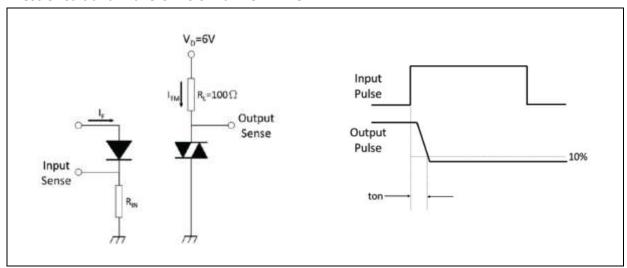




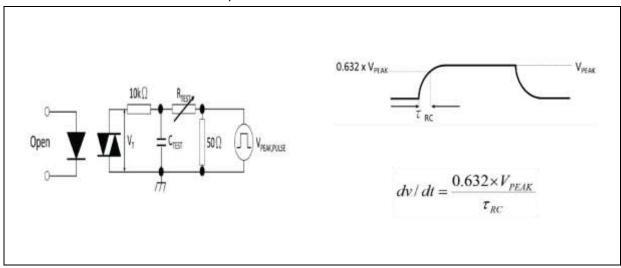


## **TEST CIRCUIT:**

## Test Circuit and Waveforms of Turn On Time:



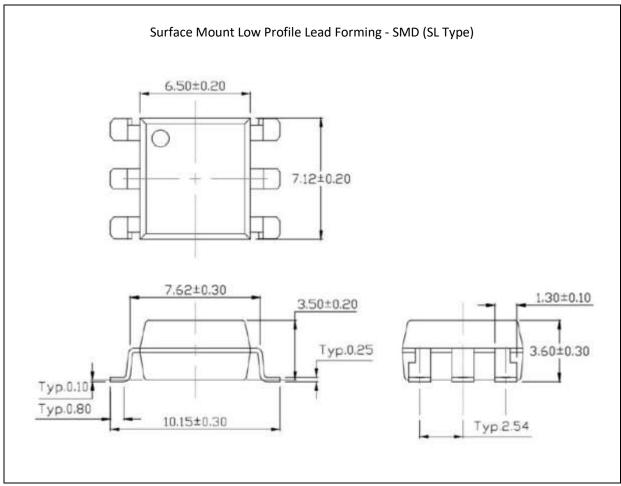
## Test Circuit and Waveforms of dV/dt:





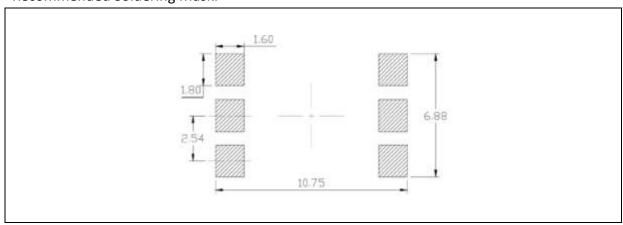
## **OUTLINE DIMENSION:**

## Package Dimension:



1. All dimensions are in millimetre (mm).

## Recommended Soldering Mask:

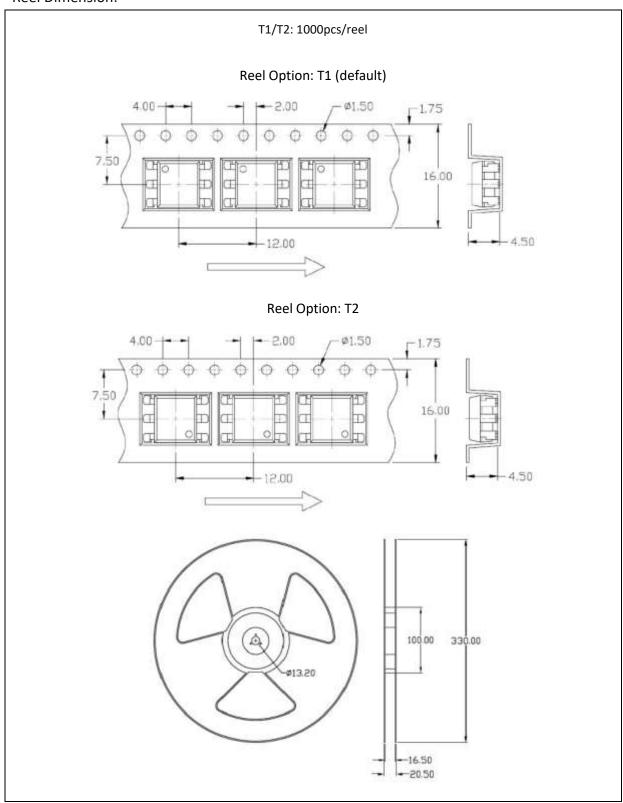


1. Dimensions are in millimetre (mm).



## **PACKING SPECIFICATION:**

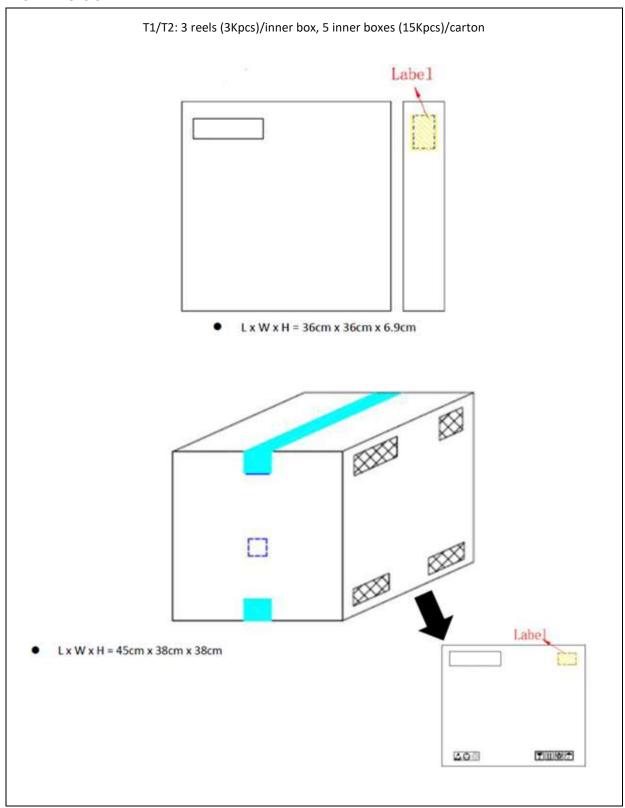
#### Reel Dimension:





## **PACKING SPECIFICATION:**

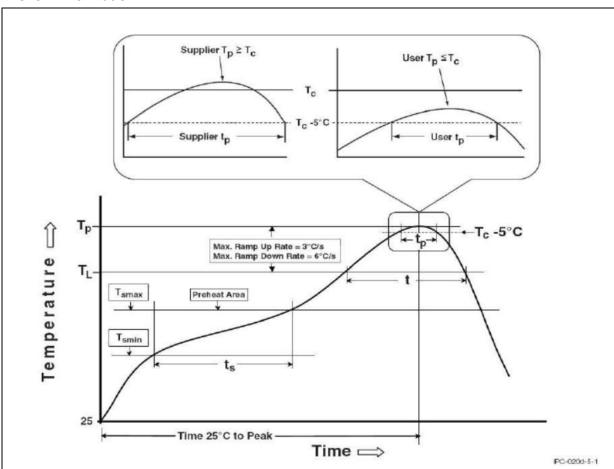
#### Box Dimension:





## **RECOMMENDED SOLDERING PROFILE:**

#### **Reflow Information:**

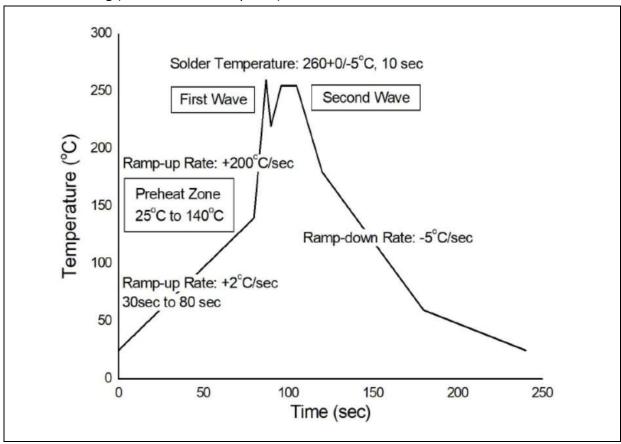


Profile Feature	Sn-Pb Assembly Profile	Pb-Free Assembly Profile
Temperature Min. (T <sub>smin</sub> )	100°C	150°C
Temperature Max. (T <sub>smax</sub> )	150°C	200°C
Time (t <sub>s</sub> ) from (T <sub>smin</sub> to T <sub>smax</sub> )	60-120 seconds	60-120 seconds
Ramp-up Rate (t∟ to t <sub>P</sub> )	3°C/second max.	3°C/second max.
Liquidous Temperature (T <sub>L</sub> )	183°C	217°C
Time (t <sub>L</sub> ) Maintained Above (T <sub>L</sub> )	60-150 seconds	60-150 seconds
Peak Body Package Temperature	235°C +0°C / -5°C	260°C +0°C / -5°C
Time (t <sub>P</sub> ) within 5°C of 260°C	20 seconds	30 seconds
Ramp-down Rate (T <sub>P</sub> to T <sub>L</sub> )	6°C/second max.	6°C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.



#### **RECOMMENDED SOLDERING PROFILE:**

## Wave Soldering (JESD22-A111 Compliant):



## Hand Soldering:

Soldering Temperature	380±5°C
Soldering Time	3 sec max.

#### Note:

- One time soldering is recommended for all soldering methods.
- Do not solder more than three times for IR reflow soldering.